1 Package summary

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>package length</td>
<td>18.85</td>
<td>19</td>
<td>19.15</td>
<td>mm</td>
</tr>
<tr>
<td>package width</td>
<td>18.85</td>
<td>19</td>
<td>19.15</td>
<td>mm</td>
</tr>
<tr>
<td>seated height</td>
<td>-</td>
<td>1.97</td>
<td>2.12</td>
<td>mm</td>
</tr>
<tr>
<td>nominal pitch</td>
<td>-</td>
<td>0.8</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>actual quantity of termination</td>
<td>-</td>
<td>525</td>
<td>-</td>
<td></td>
</tr>
</tbody>
</table>
2 Package outline

Figure 1. Package outline FBGA525 (SOT1655-5)
3 Soldering

PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER-SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 13 SEP 2022

MECHANICAL OUTLINE
PRINT VERSION NOT TO SCALE

STANDARD:
NON JEDEC

DRAWING NUMBER:
98ASA014630

REVISION:
D

Figure 2. Reflow soldering footprint part1 for FBGA525 (SOT1655-5)
Figure 3. Reflow soldering footprint part2 for FBGA525 (SOT1655-5)
Figure 4. Reflow soldering footprint part3 for FBGA525 (SOT1655-5)
H-FC-PBGA-525 I/O
19 X 19 X 1.97 PKS, 0.8 PITCH

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE
   SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE
   OF PACKAGE.
7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.
8. VENT AREA BETWEEN LID AND SUBSTRATE, SIZE MAY VARY.

Figure 5. Package outline note FBGA525 (SOT1655-5)
4 Legal information

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